

47. The bond-ply material of claim 46, wherein the conductive paste comprises a plurality of inorganic particles in a organic medium.

**IN THE SPECIFICATION**

Insert the following before "Field of the Invention":

This application is a divisional of allowed application Serial Number 09/826,718, filed April 4, 2001.

**REMARKS**

No new matter was added by this preliminary amendment.

Please use 30-4949 DIV2 - 4960 as the docket number for this application.

**REQUEST FOR ALLOWANCE**

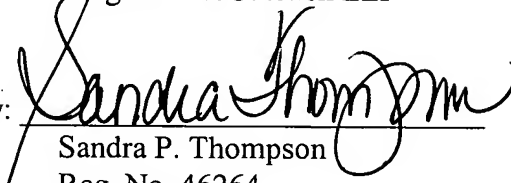
Claims 34-47 are pending in this application. The applicants request allowance of all pending claims.

Respectfully submitted,

Bingham McCutchen LLP

Dated: November 17, 2003

By:

  
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